

# SOT775A

leadless surface mounted package; plastic cap; 16 terminations

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	QMAN16
<b>Package type industry code</b>	QMAN16
<b>Package style descriptive code</b>	QMAN (quad microelectronic assembly; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.8	-	8	8.2	mm
E	package width	7.8	-	8	8.2	mm
A	seated height	[tbd]	-	1.6	1.6	mm
n <sub>2</sub>	actual quantity of termination	-	-	16	-	



## 2. Package outline

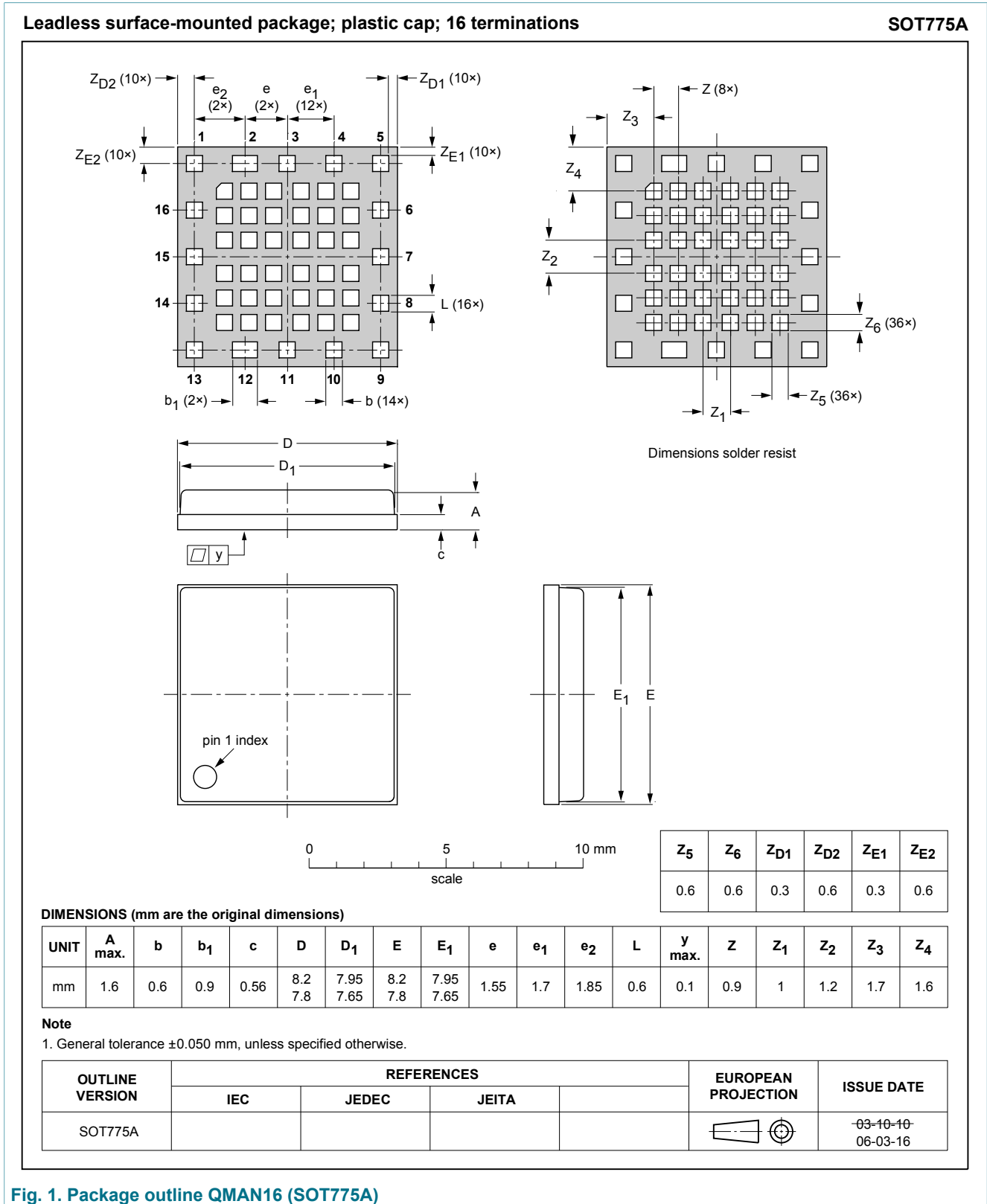


Fig. 1. Package outline QMAN16 (SOT775A)

### 3. Soldering

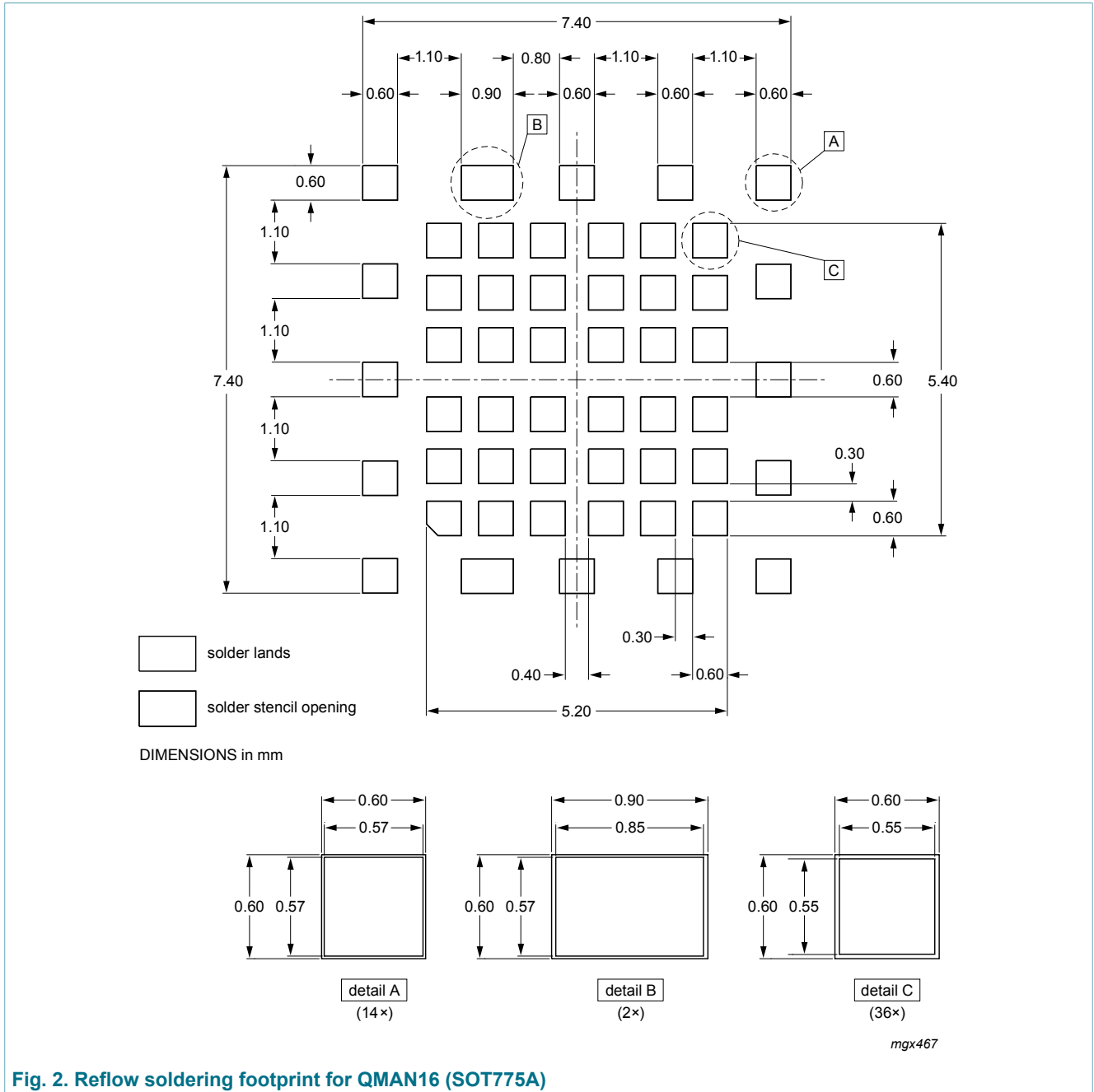


Fig. 2. Reflow soldering footprint for QMAN16 (SOT775A)

## 4. Legal information

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